

<b>Name</b>	<b>Title</b>	<b>Date</b>	<b>Time (US EDT)</b>
Keynote Week 1	What the Chiplet-Based Future of Compute Means for Components and Technology	June 1	8:00 PM
Special Session	Rising to the Chiplet Challenge	June 2	9:00 AM
Special Panel	Market Trends & Geopolitical & Economic Outlook	June 2	8:00 PM
Plenary	Transformation of the Electronics Industry in a Post-Covid World	June 3	11:00 AM
Special Session	Test in Heterogenous Integration	June 4	9:00 AM
EPS President's Panel	Future Vision of Electronics Packaging – Industry Perspective	June 7	11:00 AM
Special Session	Low Temperature Solder (LTS) – Packaging Challenges of a Next-Generation SMT Interconnect	June 7	6:00 PM
Special Session	Materials and Technologies for Advanced Packaging (5G, RF, Power, Harsh Environment)	June 8	10:00 AM
Diversity Panel	Diversity Does Matter and Can Drive Enhanced Business Performance	June 9	11:00 AM
Special Session	Home Use Medical Devices and Packaging in Wearable Technologies	June 9	8:00 PM
Keynote Week 2	Transitioning to a Renewable Energy-Based Grid	June 10	1:00 PM
Virtual Women's Luncheon Table	Virtual Women's Luncheon Table	June 10	2:30 PM
EPS Seminar	Latency: Are High-Bandwidth Optical Networks a Silver Bullet?	June 10	7:00 PM
Special Session	Pathogen Detection and Eradication	June 11	11:00 AM
Young Professionals Meetup	Career Development/Growth for Young Professionals	June 11	2:00 PM
HIR Workshop	Heterogeneous Integration Roadmap	On-demand	On-demand